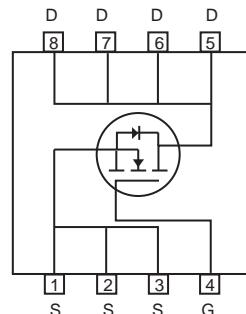
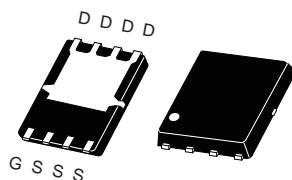


## N-Channel Enhancement Mode Field Effect Transistor

### FEATURES

- 40V, 121A,  $R_{DS\ (ON)} = 2.4\ mW$  @  $V_{GS} = 10V$ .
- $R_{DS\ (ON)} = 3.5\ mW$  @  $V_{GS} = 4.5V$ .
- Super high dense cell design for extremely low  $R_{DS(ON)}$ .
- High power and current handing capability.
- Pb-free lead plating ; RoHS compliant.
- Halogen Free.
- Surface mount Package.



P-PAK 5X6

### ABSOLUTE MAXIMUM RATINGS $T_C = 25^\circ C$ unless otherwise noted

Parameter	Symbol	Limit	Units
Drain-Source Voltage	$V_{DS}$	40	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D @ R_{qJC}$	121	A
Drain Current-Continuous	$I_D @ R_{qJA}$	40	A
Drain Current-Pulsed <sup>a</sup>	$I_{DM} @ R_{qJC}$	484	A
Drain Current-Pulsed <sup>a</sup>	$I_{DM} @ R_{qJA}$	160	A
Maximum Power Dissipation	$P_D$	56	W
Single Pulsed Avalanche Energy <sup>d</sup>	$E_{AS}$	312.5	mJ
Single Pulsed Avalanche Current <sup>d</sup>	$I_{AS}$	25	A
Operating and Store Temperature Range	$T_J, T_{stg}$	-55 to 150	°C

### Thermal Characteristics

Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Case	$R_{qJC}$	2.2	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{qJA}$	20	°C/W



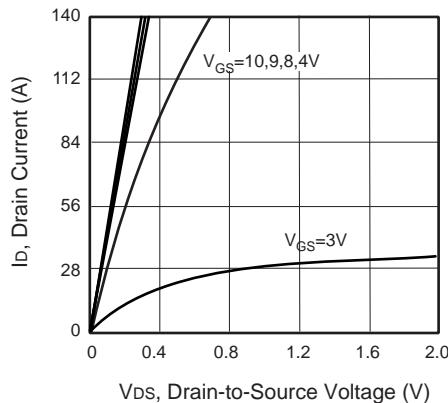
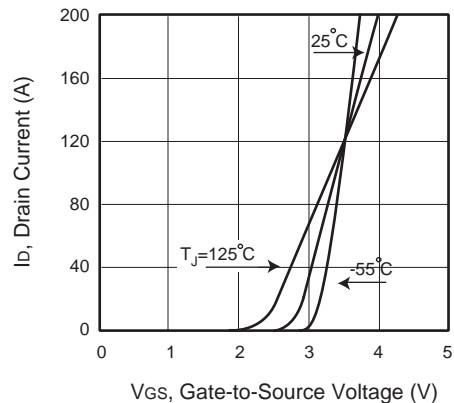
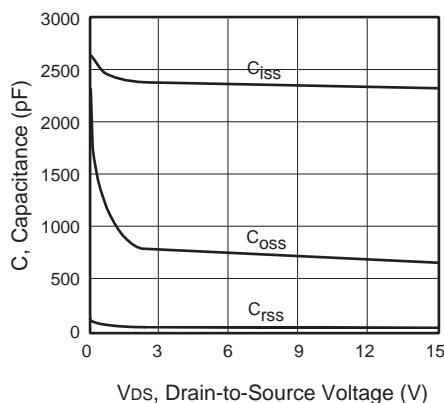
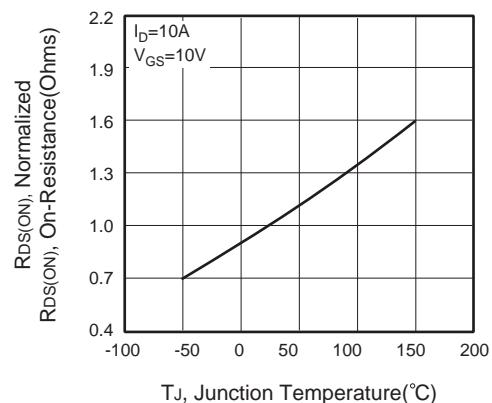
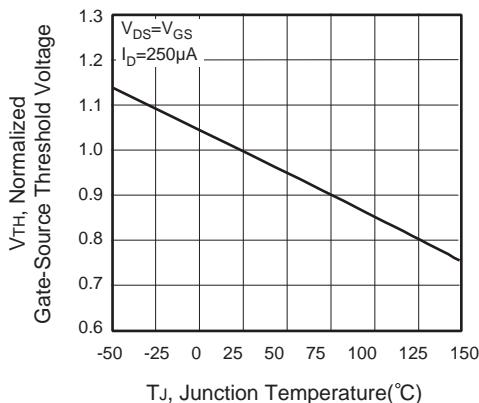
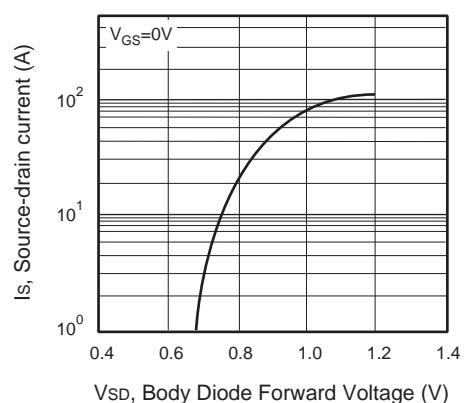
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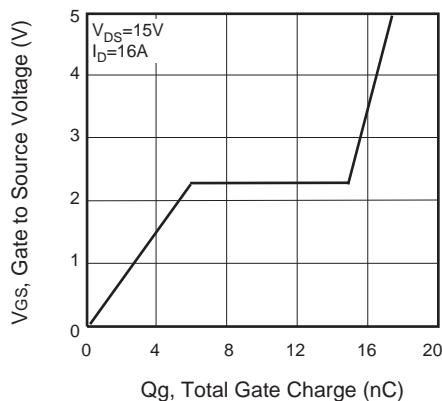
**Electrical Characteristics**  $T_C = 25^\circ\text{C}$  unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	40			V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 40\text{V}, V_{\text{GS}} = 0\text{V}$		1		$\mu\text{A}$
Gate Body Leakage Current, Forward	$I_{\text{GSSF}}$	$V_{\text{GS}} = 20\text{V}, V_{\text{DS}} = 0\text{V}$		100		nA
Gate Body Leakage Current, Reverse	$I_{\text{GSSR}}$	$V_{\text{GS}} = -20\text{V}, V_{\text{DS}} = 0\text{V}$		-100		nA
<b>On Characteristics</b> <sup>b</sup>						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$	1		3	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 10\text{A}$		2.0	2.4	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}, I_D = 5\text{A}$		2.7	3.5	$\text{m}\Omega$
<b>Dynamic Characteristics</b> <sup>c</sup>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = 15\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		2325		pF
Output Capacitance	$C_{\text{oss}}$			675		pF
Reverse Transfer Capacitance	$C_{\text{rss}}$			35		pF
<b>Switching Characteristics</b> <sup>c</sup>						
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 15\text{V}, I_D = 1\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 6\Omega$		29		ns
Turn-On Rise Time	$t_r$			5		ns
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$			67		ns
Turn-Off Fall Time	$t_f$			19		ns
Total Gate Charge	$Q_g$	$V_{\text{DS}} = 15\text{V}, I_D = 16\text{A}, V_{\text{GS}} = 4.5\text{V}$		17		nC
Gate-Source Charge	$Q_{\text{gs}}$			6		nC
Gate-Drain Charge	$Q_{\text{gd}}$			9		nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Drain-Source Diode Forward Current	$I_S$				46	A
Drain-Source Diode Forward Voltage <sup>b</sup>	$V_{\text{SD}}$	$V_{\text{GS}} = 0\text{V}, I_S = 10\text{A}$			1.2	V

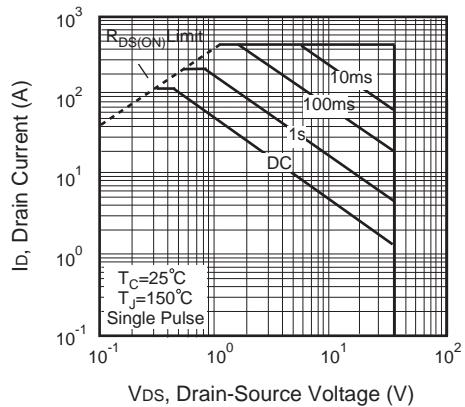
## Notes :

- a.Repetitive Rating : Pulse width limited by maximum junction temperature.
- b.Pulse Test : Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .
- c.Guaranteed by design, not subject to production testing.  
d.L = 1mH,  $I_{AS} = 25\text{A}$ ,  $V_{DD} = 24\text{V}$ ,  $R_G = 25\Omega$ , Starting  $T_J = 25^\circ\text{C}$ .

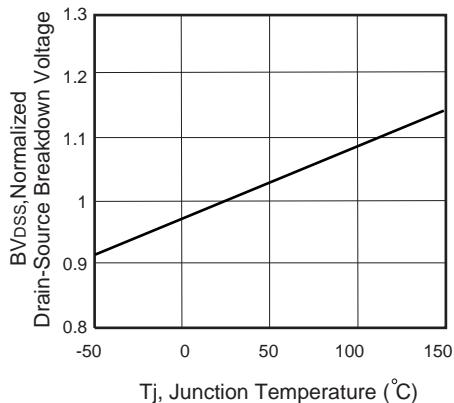
**Figure 1. Output Characteristics****Figure 2. Transfer Characteristics****Figure 3. Capacitance****Figure 4. On-Resistance Variation with Temperature****Figure 5. Gate Threshold Variation with Temperature****Figure 6. Body Diode Forward Voltage Variation with Source Current**



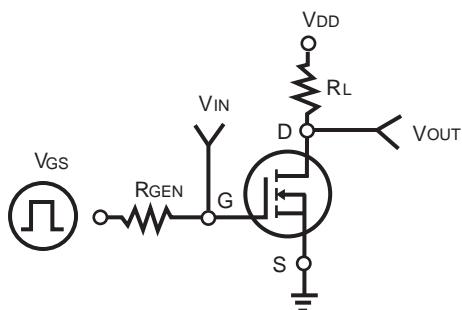
**Figure 7. Gate Charge**



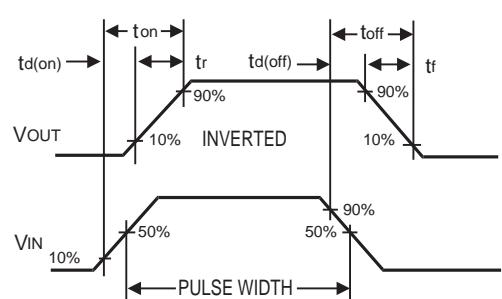
**Figure 8. Maximum Safe  
Operating Area**



**Figure 9. Breakdown Voltage Variation  
VS Temperature**



**Figure 10. Switching Test Circuit**



**Figure 11. Switching Waveforms**

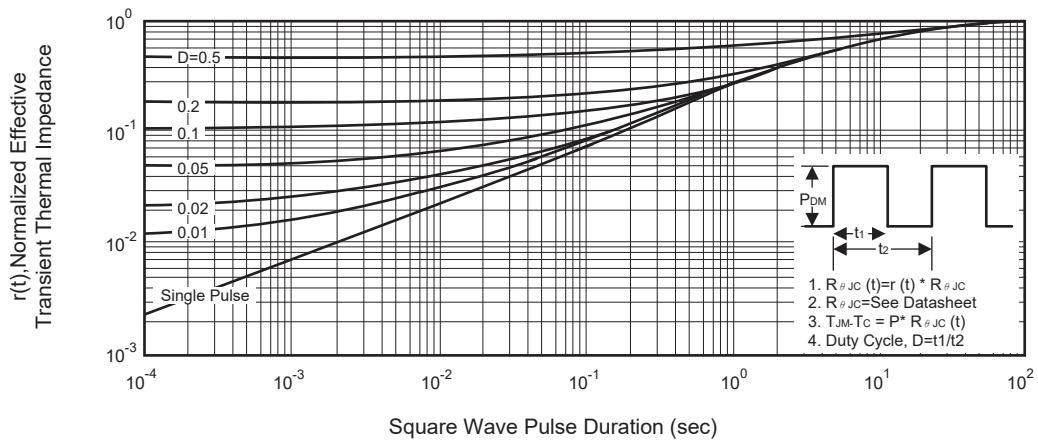
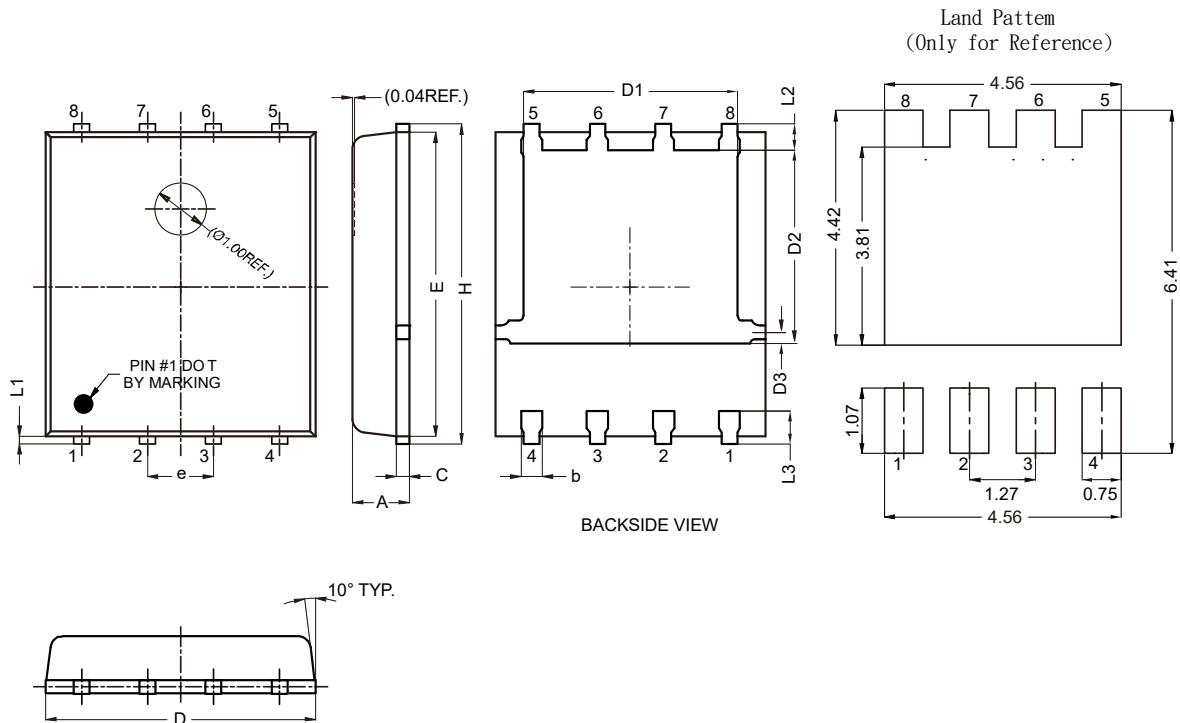


Figure 12. Normalized Thermal Transient Impedance Curve

## P-PAK5X6 產品外觀尺寸圖 (Product Outline Dimension)

## SINGLE PAD 尺寸圖



SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.000	1.200	0.039	0.047
b	0.330	0.500	0.013	0.020
c	0.200	0.300	0.008	0.012
D	5.000	5.400	0.197	0.213
D1	3.800	4.250	0.150	0.167
D2	3.520	3.920	0.139	0.154
D3	0.396	0.436	0.016	0.017
E	5.760	5.960	0.227	0.235
e	1.270 TYP		0.050 TYP	
H	6.050	6.250	0.238	0.246
L1	0.080	0.220	0.003	0.009
L2	0.400	0.600	0.016	0.024
L3	0.500	0.700	0.020	0.028